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Heng et al.

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(54) **CIRCUIT PACKAGE LID**

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(51) **LOC (9) Cl.** **13-03**
(52) **U.S. Cl.** **D13/182**
(58) **Field of Classification Search** D13/182; 439/70, 71, 72, 73, 74, 330, 331, 620.2
See application file for complete search history.

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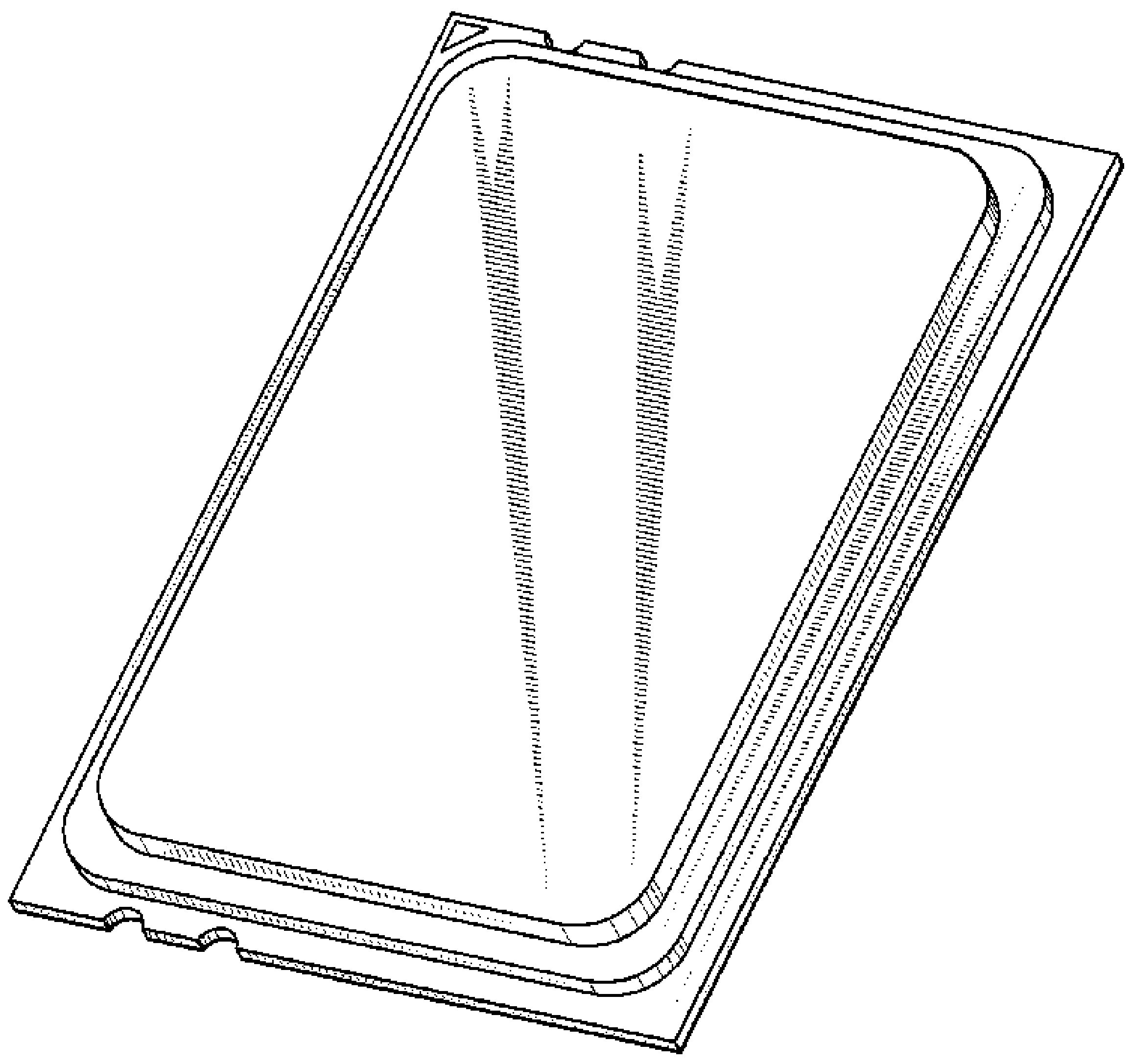
(57) **CLAIM**

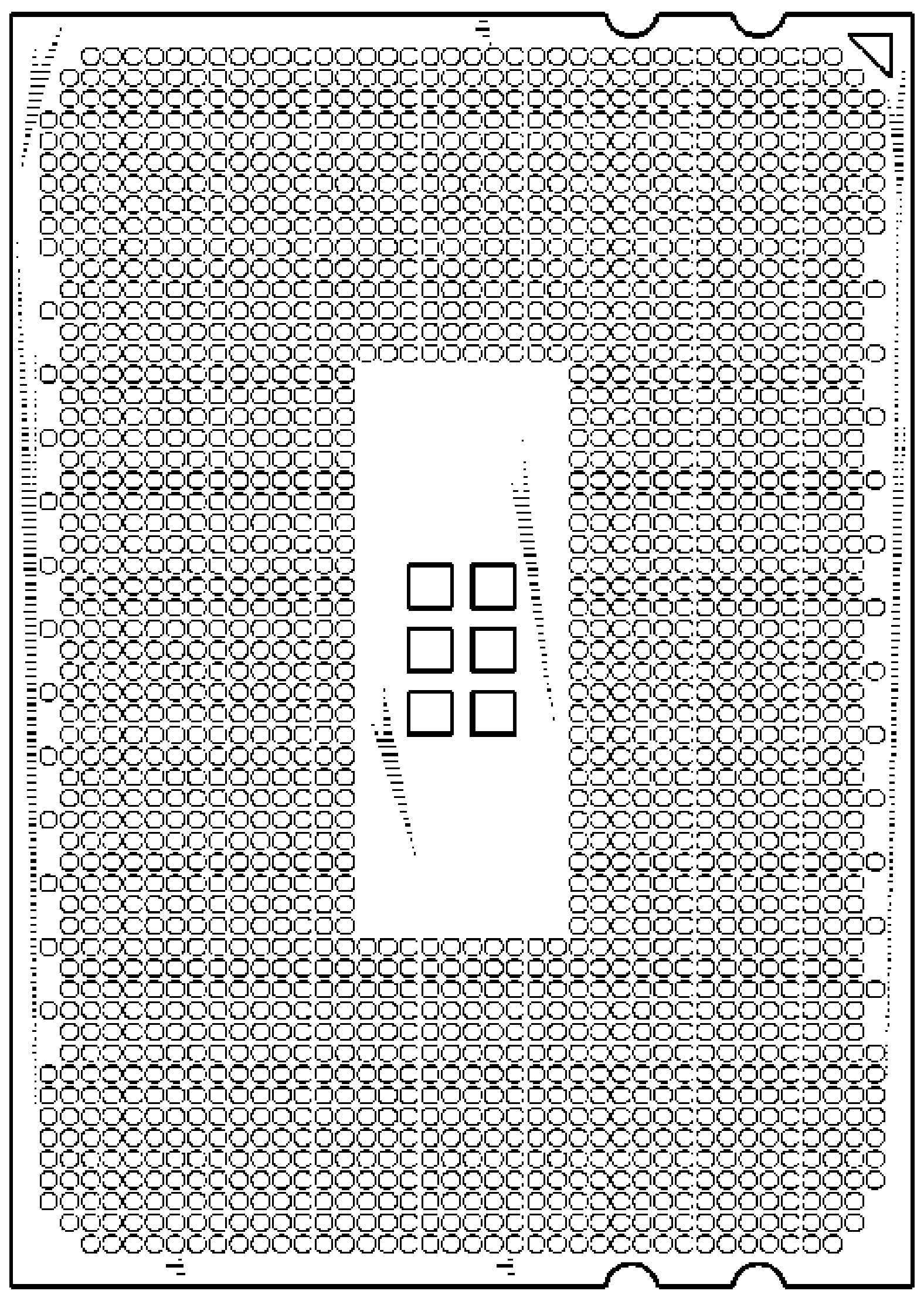
The ornamental design for a circuit package lid, as shown and described.

DESCRIPTION

FIG. **1** is a front perspective view of a circuit package lid;
FIG. **2** is a front view of the circuit package lid;
FIG. **3** is a top view of the circuit package lid;
FIG. **4** is a bottom view of the circuit package lid;
FIG. **5** is a left side view of the circuit package lid;
FIG. **6** is a right side view of the circuit package lid; and,
FIG. **7** is a rear view of the circuit package lid.

1 Claim, 3 Drawing Sheets





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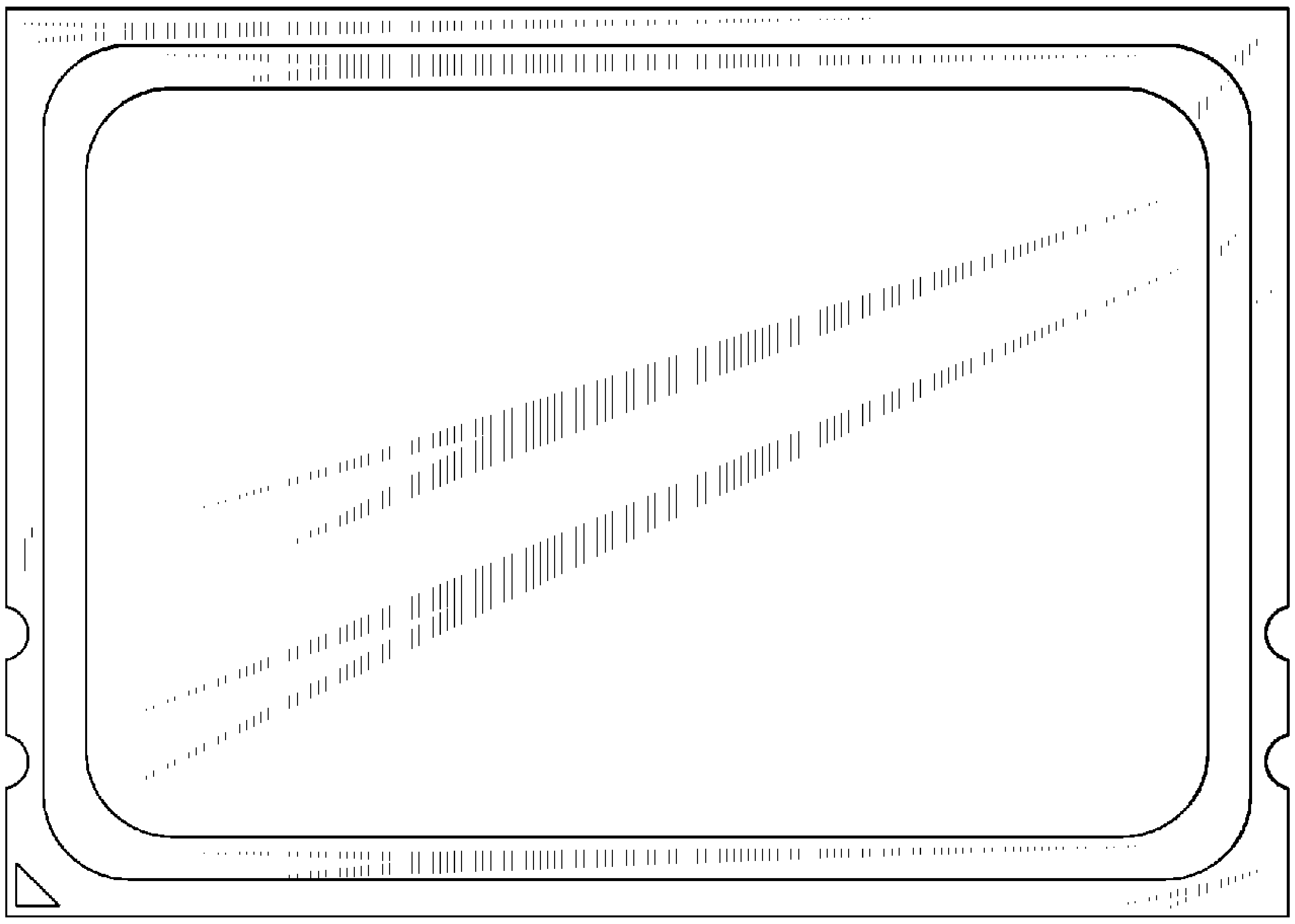

FIG. 2

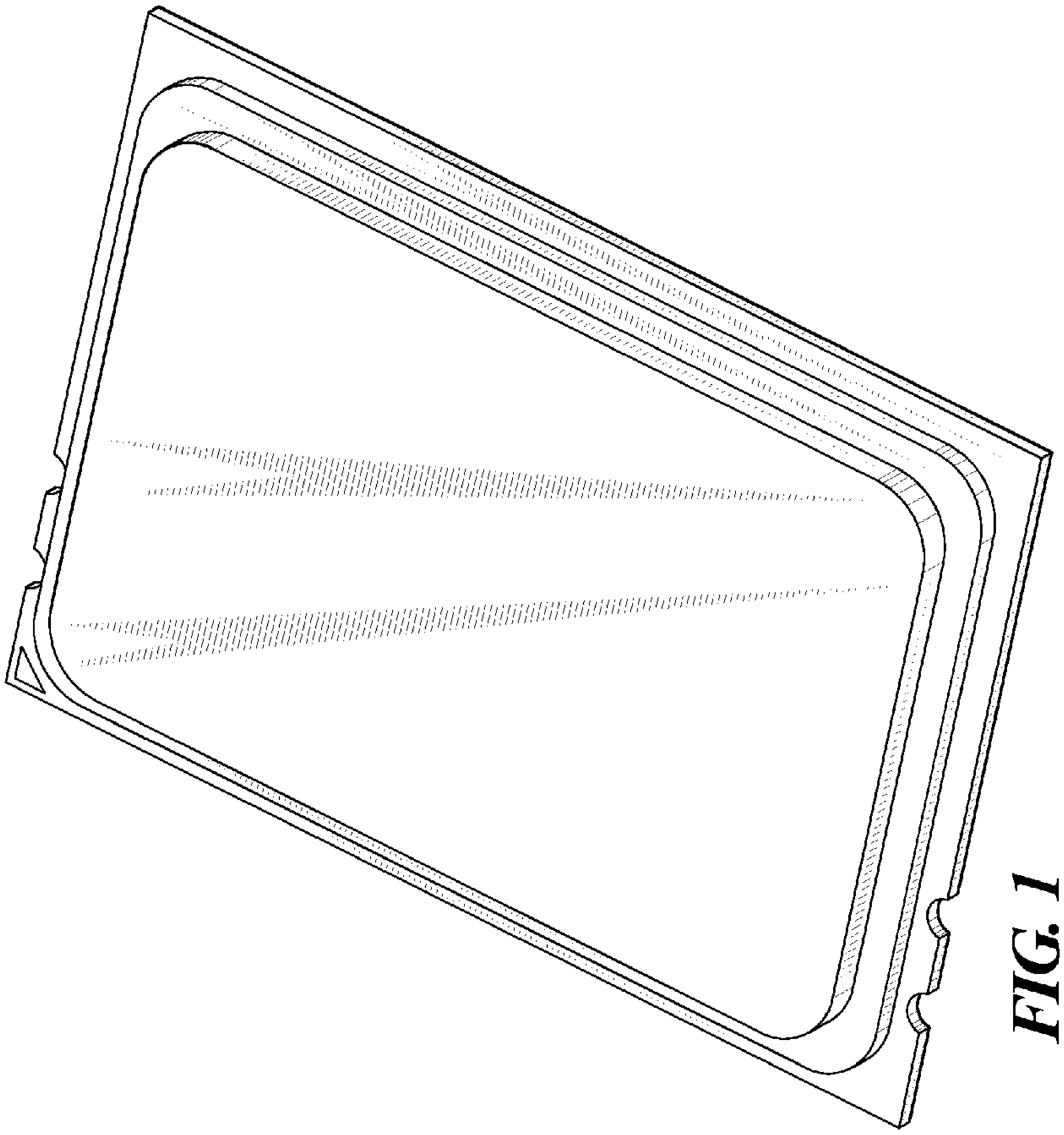

FIG. 1

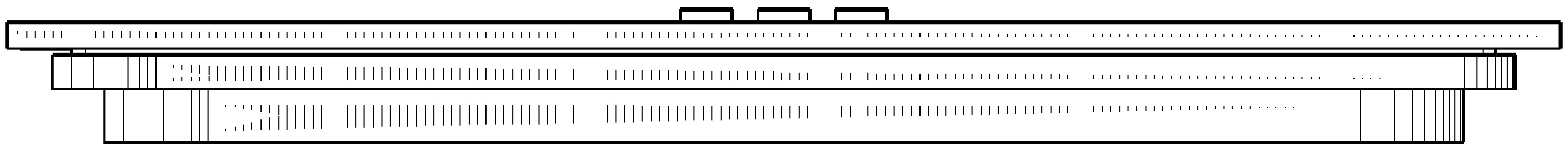

FIG. 6

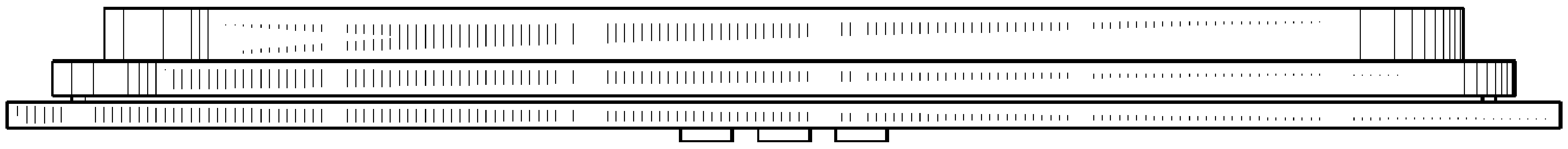

FIG. 5

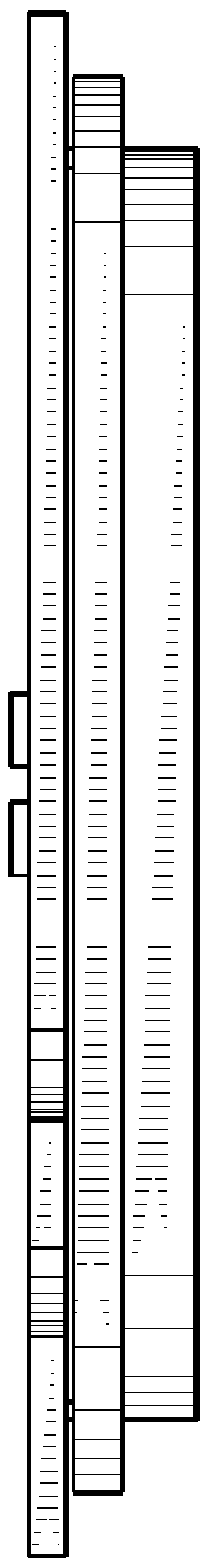

FIG. 3

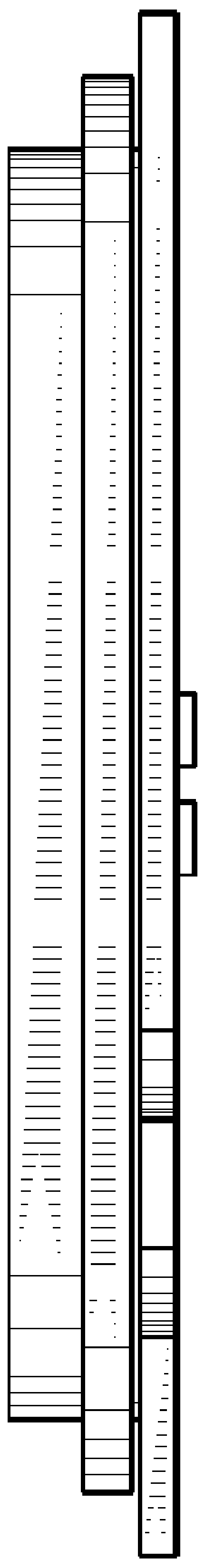

FIG. 4

FIG. 7